DESCRIPTION

~~METHOD FOR FINAL POLISHING OF SILICON WAFER, AND SILICON WAFER~~

TECHNICAL FIELD

[0001]

The present invention relates to a final polishing method of a silicon wafer and to a silicon wafer.

BACKGROUND ART

[0002]

A semiconductor wafer typified by a silicon wafer is polished with a polishing apparatus 601, as shown in FIG. 6, including a turn table 603 with a polishing pad 602 attached, a polishing-agent-supply mechanism 604, and a polishing head 606 by holding the semiconductor wafer W with the polishing head 606, supplying a polishing agent 605 from the polishing-agent-supply mechanism 604 to the polishing pad 602, separately rotating the turn table 603 and the polishing head 606, and bringing the surface of the semiconductor wafer W into sliding contact with the polishing pad 602.

[0003]

The semiconductor wafer is often polished in multiple stages with changing the kinds of the polishing pad and the polishing agent; first double-side polishing is referred to as primary polishing, polishing after the primary polishing is referred to as secondary polishing, and a polishing process in the final stage is referred to as finish polishing or final polishing.

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In the final polishing process, single-side

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